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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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MLC capacitors with silver/palladium (Ag/Pd) terminations have often been used in medical applications where non-magnetic components are required, for example in MRI equipment - however, conventional nickel barrier terminations are not suitable due to their magnetic properties. In addition, RoHS requirement to use lead-free solders would cause an increase in soldering temperatures and cause solder leaching problems for the Ag/Pd termination. This has meant alternatives have had to be found and one solution is to use a copper barrier instead of a nickel barrier, with a tin finish on top. This non-magnetic termination is offered with selected non-magnetic C0G/NP0, High Q and X7R dielectrics, providing a fully non-magnetic component ( $\mu_r = 1.0000$ ).

To meet high temperature 260°C soldering reflow profiles as detailed in J-STD-020, C0G/NP0 dielectrics are supplied with FlexiCap™ or sintered termination whilst X7R dielectrics are supplied only with the FlexiCap™ termination.

Available in chip or ribbon leaded format for certain case sizes (consult sales office).



## High Q, C0G/ NP0 - minimum/ maximum capacitance values

Chip Size	0402	0603	0505	0805	1206	1111 1210	1808	1812	2220
<b>Min Cap</b>	0.1pF	0.1pF	0.2pF	0.2pF	0.5pF	0.3pF	1.0pF	1.0pF	2.0pF
<b>50V 63V</b>	22pF	100pF	220pF	470pF	1.5nF	-	-	-	-
<b>100V</b>	15pF	68pF	150pF	330pF	1.0nF	2.2nF	2.2nF	4.7nF	10nF
<b>150V</b>	10pF	47pF	100pF	220pF	680pF	1.5nF	1.5nF	3.3nF	6.8nF
<b>200V 250V</b>	6.8pF	33pF	56pF	150pF	470pF	1.0nF	1.0nF	2.2nF	4.7nF
<b>300V</b>	-	27pF	47pF	120pF	390pF	820pF	820pF	1.8nF	3.9nF
<b>500V</b>				68pF	270pF	680pF	680pF	1.5nF	3.3nF
<b>630V</b>				-	150pF	390pF	390pF	1.0nF	2.2nF
<b>1000V</b>				-	82pF	220pF	220pF	680pF	1.5nF
<b>2000V</b>				-	18pF	68pF	68pF	150pF	470pF
<b>3000V</b>				-	-	-	-	68pF	150pF

Min Capacitance Tolerance  
±0.05pF (<4.7pF)  
0.1pF (≥4.7pF & <10pF)  
±1% (≥10pF)

## X7R - minimum/ maximum capacitance values

Chip Size	0402	0603	0805	1206	1210	1808	1812	2220
<b>Min Cap</b>	47pF	100pF	330pF	680pF	1.5nF	2.2nF	3.3nF	6.8nF
<b>16V</b>	10nF	100nF	330nF	1.0μF	1.5μF	1.5μF	3.3μF	5.6μF
<b>25V</b>	6.8nF	68nF	220nF	820nF	1.2μF	1.2μF	2.2μF	4.7μF
<b>50V 63V</b>	4.7nF	47nF	150nF	470nF	1.0μF	680nF	1.5μF	3.3μF
<b>100V</b>	1.5nF	10nF	47nF	150nF	470nF	330nF	1.0μF	1.5μF
<b>200V 250V</b>	680pF	5.6nF	27nF	100nF	220nF	180nF	470nF	1.0μF
<b>500V</b>	-	1.5nF	8.2nF	33nF	100nF	100nF	270nF	560nF
<b>630V</b>			4.7nF	10nF	27nF	33nF	150nF	330nF
<b>1000V</b>			3.3nF	4.7nF	15nF	18nF	56nF	120nF
<b>1200V</b>			-	3.3nF	10nF	10nF	33nF	82nF
<b>1500V</b>			-	2.7nF	6.8nF	6.8nF	22nF	47nF
<b>2000V</b>			-	2.2nF	4.7nF	4.7nF	10nF	27nF

Min Capacitance Tolerance  
±5%

## High Q, C0G/ NP0 High Power RF capacitors - minimum/ maximum capacitance values

A range of ultra-low loss High Q ceramic capacitors with C0G/NP0 characteristics suitable for high power applications where minimal power loss and very low self heating is demanded.

Common applications include MRI body coils and wireless charging systems operating in the kHz and MHz frequencies.

Available in chip or ribbon leaded format.

Chip size	Case size 25 - 2225		Case size 40 - 4040	
	Min.	Max.	Min.	Max.
<b>200V</b>	6.2nF	10nF	16nF	27nF
<b>500V</b>	5.1nF	5.6nF	13nF	15nF
<b>630V</b>	3.9nF	4.7nF	12nF	12nF
<b>1kV</b>	1.2nF	3.3nF	5.6nF	10nF
<b>2kV</b>	510pF	1.0nF	1.6nF	5.1nF
<b>3kV</b>	1pF	47*/470pF	910pF	1.5nF
<b>4kV</b>			620pF	820pF
<b>5kV</b>			390pF	560pF
<b>6kV</b>			160pF	330pF
<b>7.0/ 7.2kV</b>			1pF	56**/150pF

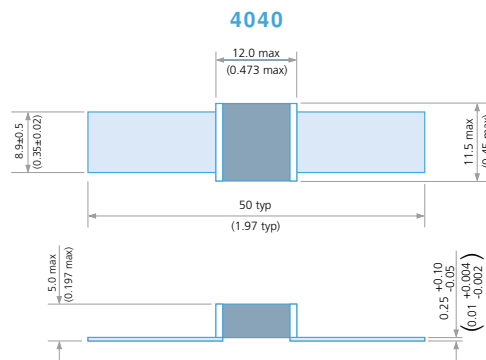
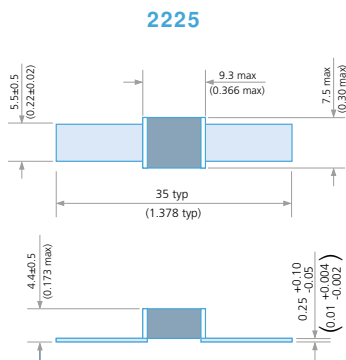
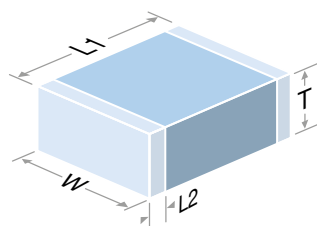
\*47pF max. for dual rated  
@2.5kVac 30MHz  
\*\*56pF max. for dual rated  
@5kVac 30MHz.



# Non-Magnetic Capacitors - High Q, C0G/NP0, X7R - 16V to 7.2kV

**Surface Mount** See page 20 for dimensions

**Ribbon Leaded** Silver plated copper ribbon attached with HMP solder - (MP greater than 260°C)



## Ordering information - Syfer Non-Magnetic capacitors

Chip size	Termination or Coating (Ribbon Leaded)	Voltage	Capacitance in picofarads (pF)	Capacitance tolerance	Dielectric	Packing	Lead Options	Suffix code
1206	2	500	0223	J	Q	T	-	-
4040	2	7K0	0470	G	Q	B	-	AF9
2225	B	3K0	6P80	G	Q	B	R	W221
0402*	2 = Sintered silver with copper barrier*	50 = 50V	<10pF Insert a P for the decimal point, eg 2P20 = 2.2pF.	<4.7pF H = ±0.05pF B = ±0.1pF C = ±0.25pF D = ±0.5pF	C = C0G/NP0 (1B) Q = High Q X = X7R (2R1)	T = 178mm (7") reel R = 330mm (13") reel B = Bulk pack - tubs or trays	R = Ribbon lead Blank = SM chip	W221 = Leaded W211 = Leaded marked
0603	3 = FlexiCap™ with copper barrier.	100 = 100V	>10pF. 1st digit is 0. 2nd and 3rd digits are significant figures of capacitance code. The 4th digit is number of 0's following	≥4.7pF ~ <10pF B = ±0.1pF C = ±0.25pF D = ±0.5pF				** AF9 = SM standard chip
0505	4 = Sintered silver with copper barrier*	1K0 = 1kV	eg. 0470 = 47pF 0512 = 5100pF	≥10pF F = ±1% G = ±2% J = ±5% K = ±10% M = ±20%				** AF9LM = SM marked standard chip
0805	5 = FlexiCap™ base with copper barrier.	2K0 = 2kV	Values <1pF in 0.1pF steps, above this values are E24 series					
1206	Ribbon Leaded	3K0 = 3kV						
1111	B = Uncoated	4K0 = 4kV						
1210	V = Coated with modified silicone laquer	5K0 = 5kV						
1808		6K0 = 6kV						
1812		7K0 = 7kV						
2220								
2225†								
4040†								

Note: \*0402 - C0G/NP0 and High Q only. †Ribbon Leads available. \*\*AF9 and AF9LM suffix code only available in 1111, 2225 and 4040 chip sizes.

## Ordering information - Voltronics Non-Magnetic capacitors

Chip size	Capacitance	Tolerance	Voltage	Termination	Material	Lead/Packaging
11	470	J	1000	W	F	R
4 0402*	0R1 0.1pF	A ±0.05pF	50 = 50V	W = Ag/Cu/Sn	Q = High Q 0±30ppm/°C	R = Ribbon
5 0505	100 10pF	B ±0.1pF	100 = 100V	S = Pd/Ag	X = X7R (2R1)	T* = Tape & Reel
6 0603*	101 100pF	C ±0.25pF	1000 = 1000V	M = Poly/Cu/Sn		B* = Bulk
8 0805*	102 1000pF	D ±0.5pF		2 = Ag/Cu/Sn - (Q dielectric only)		
11 1111†		F ±1%		3 = Poly/Cu/Sn - (X dielectric only)		
12 1206*		G ±2%		B = Silver - (Q ribbon only)		
13 1210*		J ±5%		V = Silver, laquer Coated - (Q ribbon only)		
18 1812*		K ±10%				
22 2220*		M ±20%				
25 2225†						
38 3838†						
40 4040†						

Note: \*Q and X dielectric only. †Ribbon Leads available.



# Non-Magnetic Capacitors, High Power RF - Porcelain High Q

Made from highly stable, low loss dielectric formulations, these traditional porcelain MLCs are known for their high RF power handling capability. Available in all industry common case sizes. The special silver-palladium termination and the proprietary ceramic formulations guarantee consistent non-magnetic performance. All MLCs in these series are RoHS compliant. Chips are available either with standard termination or can be fitted with ribbon leads, depending on your application.

## Description

- Porcelain Capacitors • Zero TC • Low Noise • Low ESR, High Q
- High Self-resonance • Established Reliability
- Capacitance range 0.1pF to 5.1nF

## Functional Applications

- Impedance Matching • DC Blocking • Bypass • Coupling
- Tuning and Feedback



## High Power RF capacitors - F & H materials - Minimum/ maximum capacitance values - see ordering information

Chip Size	Case size 5 0505		Case size 11 1111		Case size 25 2225		Case size 38 3838	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
50V	-	-	680pF	1nF	-	-	-	-
100V	-	-	510pF	620pF	-	-	-	-
200V	36pF	100pF	220pF	470pF	-	-	-	-
250V	0.1pF	33pF	-	-	-	-	-	-
300V	-	-	-	-	2.2nF	2.7nF	-	-
500V	-	-	110pF	200pF	1.5nF	1.8nF	2.7nF	5.1nF
1kV	-	-	0.1pF	100pF	510pF	1.2nF	750pF	2.2nF
1.5kV	-	-	-	-	300pF	470pF	-	-
2kV	-	-	-	-	-	-	-	-
2.5kV	-	-	-	-	0.3pF	270pF	430pF	680pF
3.6kV	-	-	-	-	-	-	110pF	390pF
7.2kV	-	-	-	-	-	-	0.3pF	100pF

Note: Special capacitance values available upon request.

## Ordering information - Non-Magnetic capacitors

11	470	J	1000	W	F	R
Chip size	Capacitance	Tolerance	Voltage	Termination	Material	Lead
5 0505	0R1 0.1pF	A ±0.05pF	50 50V	W Ag/ Cu/ Sn	H AH +90±20ppm/°C	B = Chip
11 1111†	100 10pF	B ±0.1pF	100 100V	S Pd/ Ag	F CF 0±15ppm/°C	R = Ribbon
25 2225†	101 100pF	C ±0.25pF	1000 1000V	M Poly/ Cu/ Sn		
38 3838†	102 1000pF	D ±0.5pF				
		F ±1%				
		G ±2%				
		J ±5%				
		K ±10%				

Note: †Available in chip or ribbon lead format.

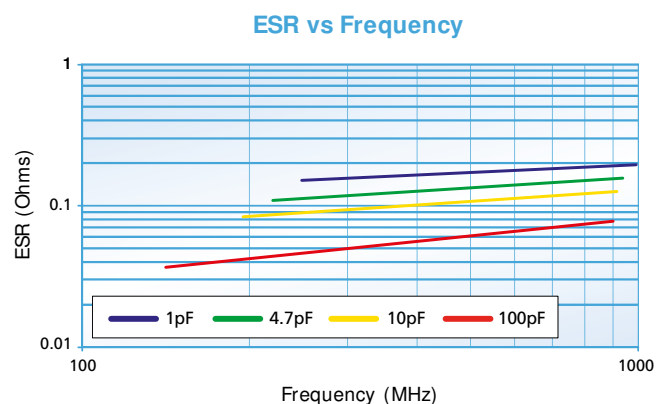
## Reeled Quantities

Chip Size	0402	0505	0603	0805	1206	1111 1210	1808	1812	2220	2225
7" Reel	10000	2500	4000	3000	2500	1000/2000	1500	500	500	500
13" Reel	13" reel quantities available on request						6000	2000	2000	2000

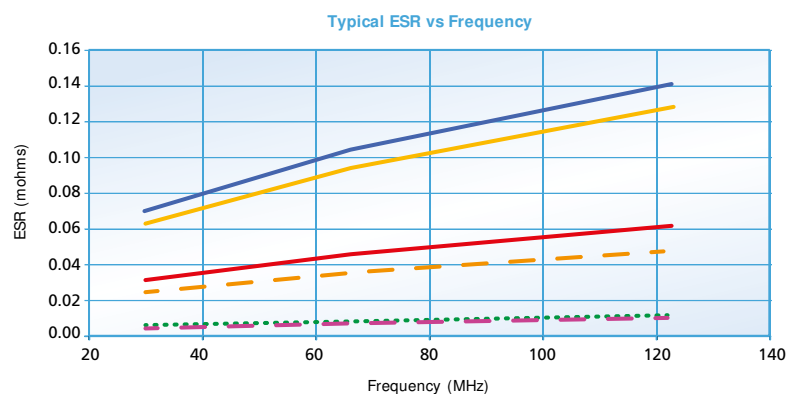
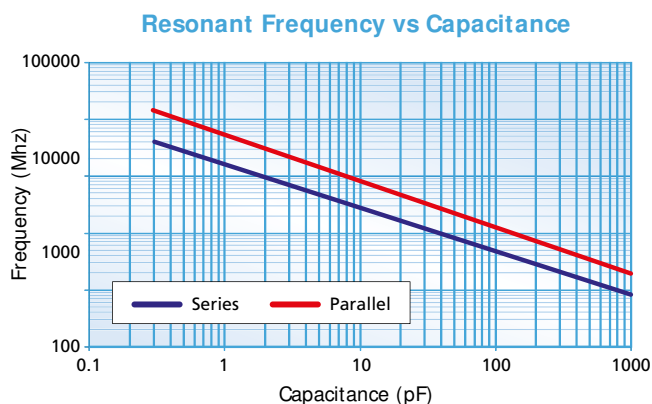
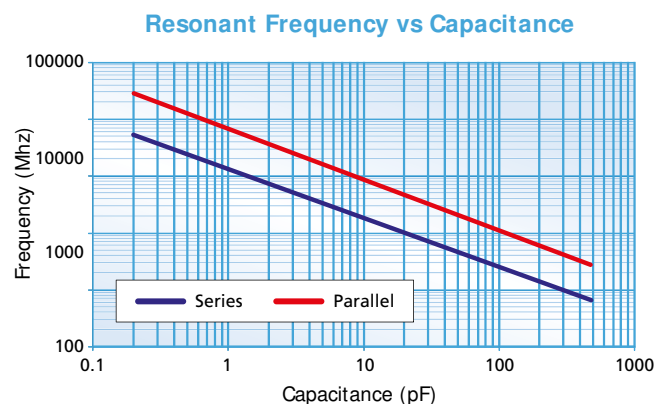
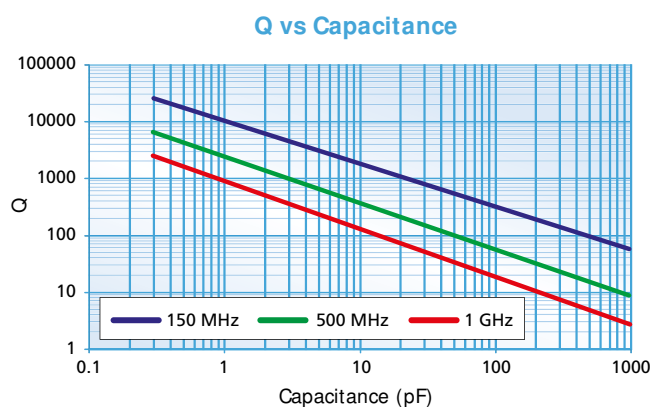
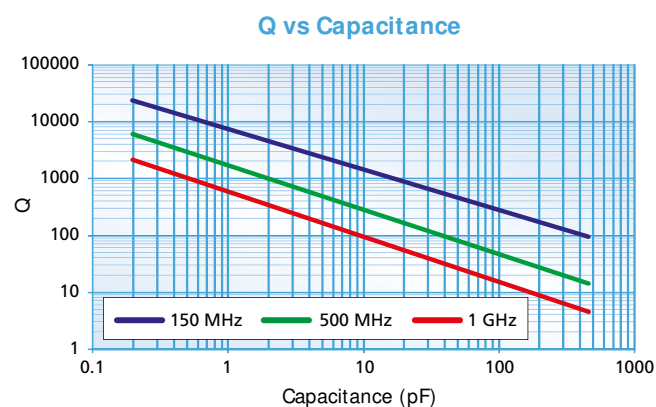
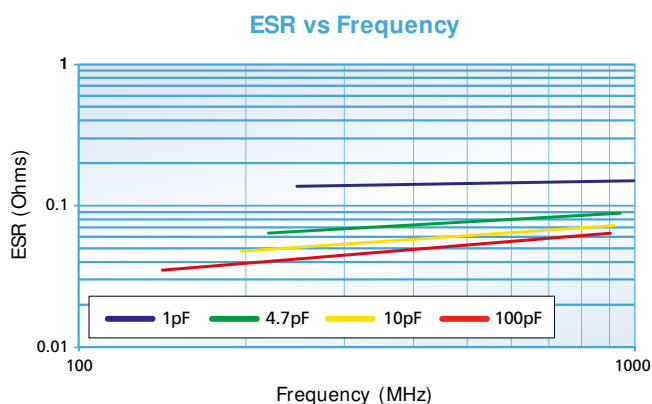
Note: Other capacitance values may become available, please contact the Sales Office if you need values other than those shown in the above tables. For dimensions and soldering information, please go to our website [www.knowlescapacitors.com](http://www.knowlescapacitors.com).

# Non-Magnetic Capacitors - High Q, X7R

Typical performance data - chip size 0805 High Q



Typical performance data - chip size 1111 High Q



- 4040 56pF
- 4040 18pF
- 2225 2.2nF
- 2225 39pF
- 2225 10pF
- 4040 5.1nF

## ESR Measurement

All ESR figures are measured using a VNA and 2m copper resonant tube and extrapolating to 30MHz by ratio. Measured data can be supplied on request. Measurement of ESR can vary with test method and components should only be compared when tested back-to-back on the same equipment under controlled conditions.